

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ050N03MS G	**Issued**	04. April 2021
MA#	MA001623880		
Package	PG-TSDSON-8-2	**Weight***	38.32 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.213	3.16	3.16	31642	31642
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		55	
	non noble metal	zinc	7440-66-6	0.008	0.02		219	
	non noble metal	iron	7439-89-6	0.168	0.44		4375	
	non noble metal	copper	7440-50-8	6.808	17.77	18.24	177652	182301
wire	non noble metal	copper	7440-50-8	0.037	0.10	0.10	966	966
encapsulation	organic material	carbon black	1333-86-4	0.035	0.09		911	
	plastics	epoxy resin	-	1.797	4.69		46893	
	inorganic material	silicondioxide	60676-86-0	15.614	40.76	45.54	407472	455276
leadfinish	non noble metal	tin	7440-31-5	0.387	1.01	1.01	10103	10103
plating	noble metal	silver	7440-22-4	0.963	2.51	2.51	25119	25119
solder	non noble metal	tin	7440-31-5	0.028	0.07		735	
	noble metal	silver	7440-22-4	0.035	0.09		919	
	non noble metal	lead	7439-92-1	1.345	3.51	3.67	35105	36759
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			28	
	non noble metal	zinc	7440-66-6	0.004	0.01		112	
	non noble metal	iron	7439-89-6	0.086	0.22		2250	
	non noble metal	copper	7440-50-8	3.501	9.14	9.37	91366	93756
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.002			49	
	non noble metal	zinc	7440-66-6	0.008	0.02		197	
	non noble metal	iron	7439-89-6	0.151	0.39		3938	
	non noble metal	copper	7440-50-8	6.127	15.99	16.40	159894	164078
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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